CELCON® M270

CELCON®

Celcon® acetal copolymer grade M270 is a lower molecular weight, high - flow grade designed for superior moldability in multi-cavity, intricate or hard to fill molds applications. Chemical abbreviation according to ISO 1043-1: POM Please also see Hostaform® C 27021.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	23	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	
Molding shrinkage, parallel	1.7	%	ISO 294-4, 2577
Molding shrinkage, normal	1.6	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	406000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	9700	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8	%	ISO 527-1/-2
Flexural modulus	399000	psi	ISO 178
Flexural stress at 3.5%	11000	psi	ISO 178
Compressive stress at 1% strain	4500	psi	ISO 604
Tensile creep modulus, 1h	334000	psi	ISO 899-1
Tensile creep modulus, 1000h	189000	psi	ISO 899-1
Charpy impact strength, 23°C	55.2	$ftlb/in^2$	ISO 179/1eU
Charpy impact strength, -30°C	51.4	$ftlb/in^2$	ISO 179/1eU
Charpy notched impact strength, 23°C	2.47	$ftlb/in^2$	ISO 179/1eA
Izod notched impact strength, 23°C	2.57	$ftlb/in^2$	ISO 180/1A
Izod notched impact strength, -30°C	2.38	$ftlb/in^2$	ISO 180/1A

Thermal properties

Melting temperature, 10°C/min	331	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	217	°F	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	313	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.61	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.667	E-4/°F	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.75	%	Sim. to ISO 62
Water absorption, Immersion 24h	0.22	%	Sim. to ISO 62
Density	0.0509	lb/in^3	ISO 1183

CELCON® M270

CELCON®

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	365	°F
Min. melt temperature	356	°F
Max. melt temperature	374	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	$2h^2$-3	s
Back pressure	580	psi
Ejection temperature	266	°F

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Continental	TST N 055 54.12	
Ford	WSK-M4D635-A3	Natural & Black
General Motors	GMW22P-POM-C4	Natural
General Motors	GMW22P-POM-C4	Black
Li Auto	Q/LiA5310020	2021 (V2)
Nissan	POM-IC3-1	
Stellantis - Chrysler	MS.50095 / CPN-2436	Natural
Stellantis - Chrysler	MS.50095 / CPN-2794	Black

Characteristics

Processing	Injection Molding
Additives	Release agent
Special characteristics	High Flow

Additional information

Injection molding

Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

CELCON® M270

CELCON®

Processing Notes

Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

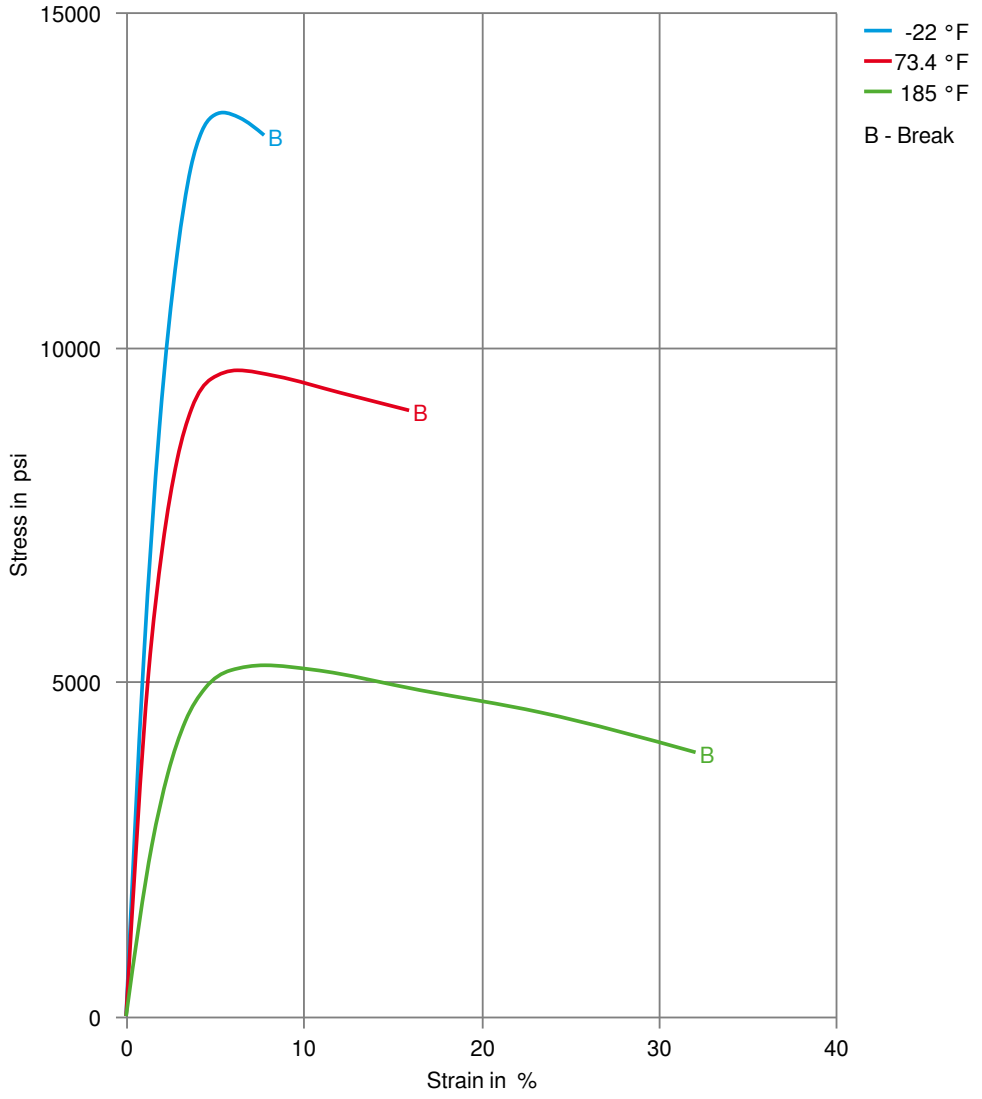
Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

CELCON® M270

CELCON®

Stress-strain

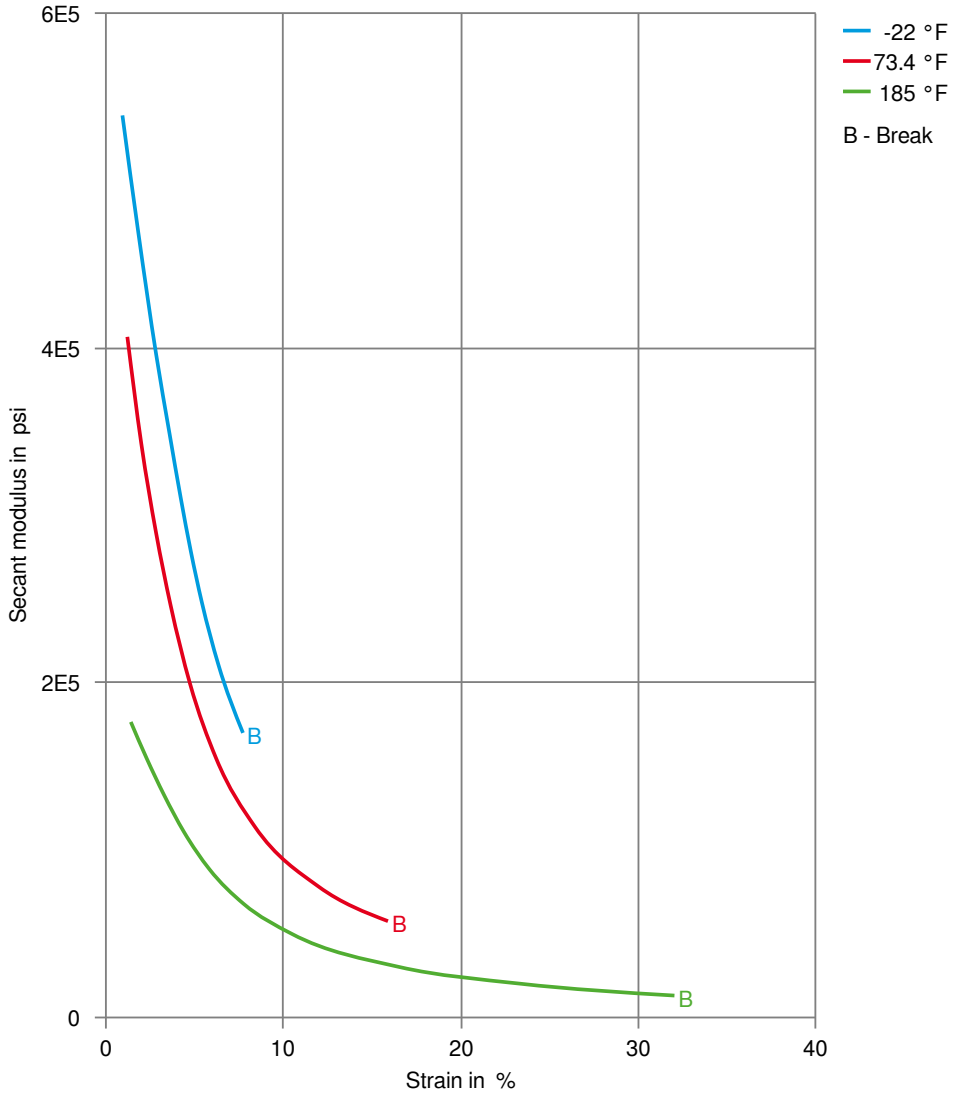


Revised: 2025-07-24 Source: Celanese Materials Database

CELCON® M270

CELCON®

Secant modulus-strain



Revised: 2025-07-24 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colorants or other additives may cause significant variations in data values. Properties of molded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.
Copyright © 2026 Celanese or its affiliates. All rights reserved.
Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates.